

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application. Please amend claim 4 as follows:

**LISTING OF CLAIMS:**

1. (Original) A thin-film magnetic head comprising:
  - an insulation gap;
  - a pair of yoke layers with one ends and the other ends, respectively, said one ends constituting magnetic poles separated with each other by said insulation gap, said the other ends being magnetically coupled with each other;
  - a coil conductor wound around at least one of said pair of yoke layers;
  - first and second trace conductors with one ends electrically connected to both ends of said coil conductor, respectively; and
  - first and second connection bumps electrically connected to the other ends of said first and second trace conductors, respectively,
  - said first trace conductor including a lower conductor layer and an upper conductor layer connected in parallel with each other, said second trace conductor including a lower conductor layer and an upper conductor layer connected in parallel with each other, said upper conductor layer of said first trace conductor and said lower conductor layer of said second trace conductor being arranged from top to bottom to face to each other, and said upper conductor layer of said second trace conductor and said lower conductor layer of said first trace conductor being arranged from top to bottom to face to each other.

2. (Original) The thin-film magnetic head as claimed in claim 1, wherein said upper conductor layer of said first trace conductor and said upper conductor layer of said second trace conductor are arranged from side to side, and wherein said lower conductor layer of said first trace conductor and said lower conductor layer of said second trace conductor are arranged from side to side.

3. (Original) The thin-film magnetic head as claimed in claim 1, wherein said first and second trace conductors are formed substantially in line to connect said coil conductor with said first and second connection bumps.

4. (Currently Amended) The thin-film magnetic head as claimed in claim 1, wherein said upper conductor layer of said first trace conductor and said upper conductor layer of said second trace conductor are exposed ~~[[outside]]~~ for connection to external circuitry.

5. (Original) The thin-film magnetic head as claimed in claim 1, wherein said first and second trace conductors are surrounded by a low dielectric constant material.